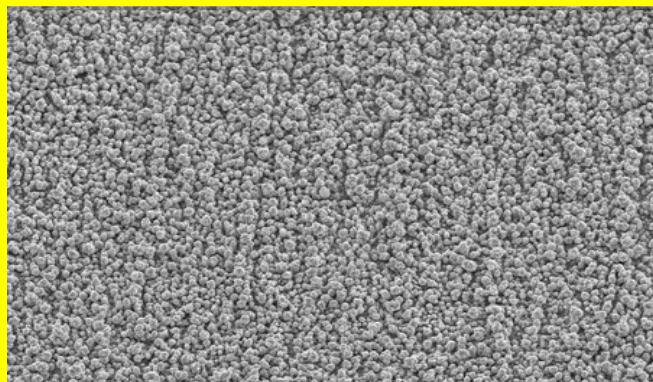
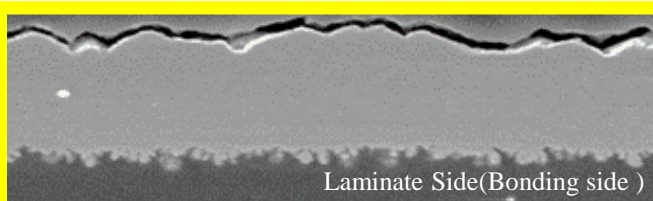


12µm untreated-side Foil SEM × 1500



12µm treated-side Foil SEM × 1500



Laminate Side(Bonding side )

12µm Foil Cross Section SEM × 1500

## Composition :

– Cross Section :



– Resist/ Bonding side Color : Pink/ Pink

## Application:

- Inner layer of Server/Switch/Storage
- HSD (High speed digital)

## Feature:

- RT311 foil with very low profile to have good etch ability, and lower electrical resistivity compared to regular ED foils.
- low profile of RT311 makes it an excellent material to apply to high speed transmission board.
- Special treatment with excellent glue overflow control ability. With high peel especially for Mid & High Tg prepreg material and Mid-Loss material.
- Micro dendrite treated, enhance etching ability and anti- undercut ability for fine line process, suitable for HDI and SI motherboard .
- Excellent anti-oxidation and shelf life.

Type	RT311		Thickness	Physical Properties						Roughness JIS94 (µm)		
				Area Wt.	Tensile(kg/mm <sup>2</sup> )		Elongation(%)		Peel Strength FR4*1		Rz (Treated side)	Rz (Untreated side)
	(oz)	(µm)	(µm)	(g/m <sup>2</sup> )	RT	180°C	RT	180°C	(lb/inch)	kg/cm		
RT311 (Pink Color)	Qoz	9µ	9±1.0	85±3	≥29	≥17	≥3	≥2	≥4.0	≥0.71	≤3.0	≤4.5
	Toz	12µ	12.3±1.5	107±3	≥29	≥17	≥4	≥3	≥4.5	≥0.80	≤3.0	≤5.0
	Joz	15µ	15±1.7	125±3	≥29	≥17	≥4	≥4	≥5.0	≥0.89	≤3.0	≤5.5
	Hoz	18µ	18±2.0	153±3	≥29	≥17	≥4	≥4	≥5.0	≥0.89	≤3.0	≤6.0
	Moz	19µ	19±1.9	158±3	≥29	≥17	≥4	≥4	≥5.0	≥0.89	≤3.0	≤6.0
	1oz	35µ	35±3.5	285±5	≥29	≥17	≥10	≥5	≥7.0	≥1.25	≤3.0	≤8.0
	Voz	36µ	36±3.6	325±5	≥29	≥17	≥10	≥5	≥7.5	≥1.34	≤3.0	≤9.0
	2oz	70µ	70±7.0	580±15	≥26	≥15	≥10	≥6	≥9.0	≥1.61	≤3.0	≤11.0
	Loz	71µ	71±7.0	605±15	≥26	≥15	≥10	≥6	≥9.5	≥1.70	≤3.0	≤11.5
	3oz	105µ	105±10.0	880±15	≥26	≥15	≥12	≥8	≥11	≥1.96	≤3.0	≤14.0

※ FR4 \*1 : Tg ≒ 140°C ※ This is representative data, not guarantee.

The best application of the copper foil manufacturer & service provider